

Device Material Content

5555 NE Moore Ct. Assembly: ASEM Hillsboro OR 97124 Package Code: Size (mm): 35 x 35 FN1152 1152 fpBGA custreg@latticesemi.com Package: Lead pitch (mm): 1.0 **Total Device Weight** 5.50 Grams **Products:** MSL: 3 June, 2022 FE2 Reflow max (°C): 250 % of Total % of Total Weight (g) Weight (g) CAS# Substance % of Subst. Notes / Assumptions: Pkg. Wt. Pkg. Wt. Die 4.04% 0.2222 Die size: 5.66 x 6.71mm 4.04% 0.2222 Silicon chip 7440-21-3 100.00% 34.46% 1.8951 Mold Compound: Sumitomo G750SE Mold Compound 2.41% 0.1327 7.00% Epoxy Resin 1.72% 0.0948 Phenol Novolac 9003-35-4 5.00% 1.72% 0.0948 Metal Hydroxide 5.00% 0.17% 0.0095 Carbon Black 1333-86-4 0.50% Silica Fused 28.43% 1.5634 60676-86-0 82.50% D/A Epoxy 0.57% 0.0314 Die attach epoxy: Henkel (Ablebond) 2100A 0.46% 0.02508 Silver 7440-22-4 80.00% 0.11% 0.00627 Esters & resins 20.00% Wire 0.18% 0.0100 0.8 mil diameter; 1 wire per solder ball 0.18% 0.0098 Copper 7440-50-8 98.50% 0.00% 0.0001 Palladium 7440-05-3 1.50% Solder Balls 20.33% 1.1181 SAC305 19.62% 1.0790 Tin (Sn) 7440-31-5 96.50% 0.61% 0.0335 Silver (Ag) 7440-22-4 3.00% 0.10% 0.0056 Copper (Cu) 7440-50-8 0.50% Substrate 21.65% 1.1909 BT Resin CCL-HL832NX-A 6.93% 0.3811 BT Resins 32.00% 14.72% 65997-17-3 0.8098 Glass fiber 68.00% Foil 14.44% 0.7941 13.64% 0.7503 Copper 7440-50-8 94.48% Nickel plating 0.72% 0.0398 7440-02-0 5.01% 0.07% 0.0040 Gold plating 7440-57-5 0.50% Solder Mask 4.33% 0.2381 Solder mask PSR4000 AUS 308 14808-60-7 2.43% 0.1338 Quartz 56.20% 0.0381 3-methoxy-3-methylbutylacetate 0.69% 103429-90-9 16.00% 0.95% 0.0524 Barium Sulfate 7727-43-7 22.00% 0.13% 0.0071 Talc (containing no asbestiform fibers) 14807-96-6 3.00% 0.12% 0.0067 Trade secret ingredients 2.80%

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